

1. Disassembly Procedures

Note: The disassembly procedure for AW2521HF/ AW2521HFL/ AW2521HFA/ AW2521HFLA is the same. The difference is only the appearance color. The actual color of AW2521HF/ AW2521HFA is black, but AW2518HFL/ AW2521HFLA is Lunar Light.

S1 Turn off the monitor.

S2 Place the monitor on a soft cloth or cushion.

Carefully slide and remove the I/O cover from the monitor



S3 Disconnect the cables from the monitor and slide them out through the cable-management slot on the stand riser.



S4 Press and hold the stand release button.



S5 Lift the stand up and away from the monitor



S6 Unlock 4 screws on Rear Cover

Use hands or scraper bar to disassemble Rear Cover from monitor

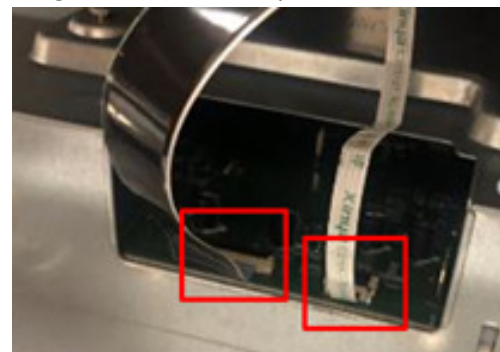
Notice the disassembly order:

Top Side=>Right/ Left Side=>Bottom Side



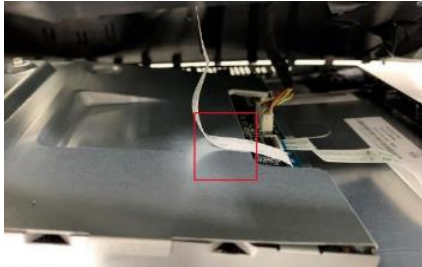
(Screw Torque: 8~10kgf)

S7 Remove USB FFC Cable and Audio FFC cable from the I/F BD

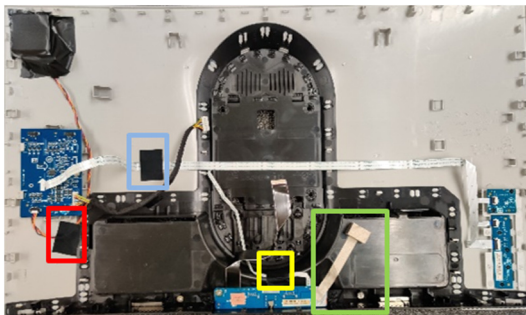


S8 Remove CTRL FFC Cable from I/F BD

Tear off an adhesive tape and remove the LED Driver BD wire from I/F BD



S9 Tear off all adhesive tapes from Rear Cover

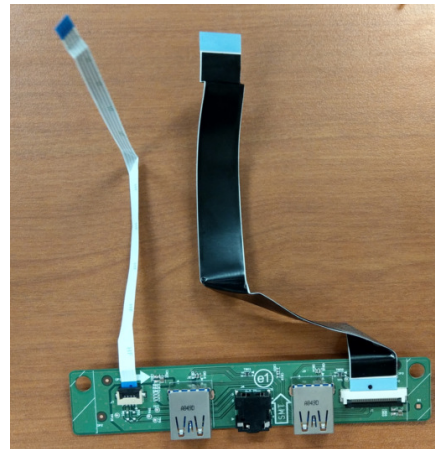


S10 Unlock 2 USB screws to disassemble USB BD from Rear Cover



(Screw Torque: 4.5±0.5Kg kgf)

S11 Disassemble “USB FFC cable” and “Audio FFC cable” from USB BD

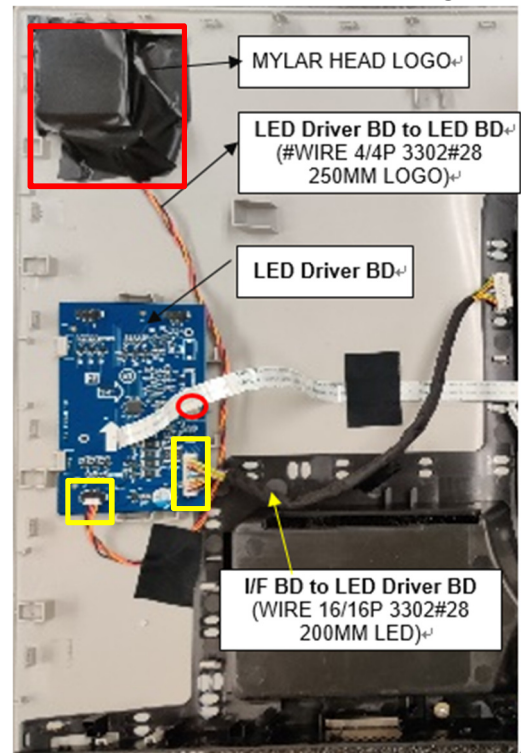


S12 Unplug wires from LED Driver BD

Unlock 1 screw to disassemble LED Driver BD from Rear Cover

Tear off “MYLAR HEAD LOGO” from LED Logo Lens

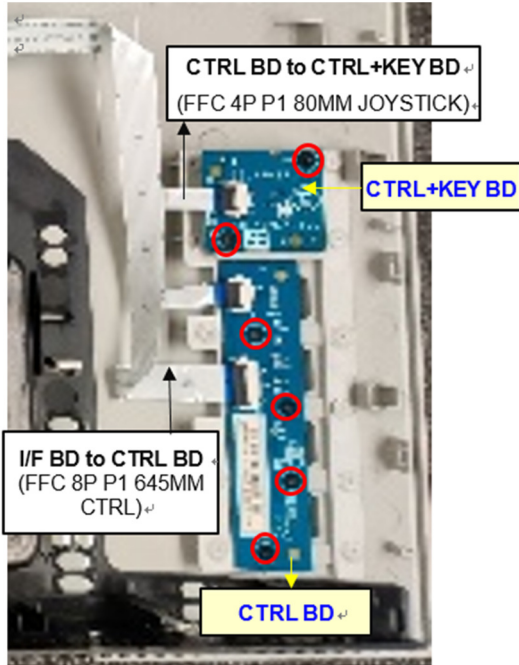
Unplug wire from LED BD and disassemble LED BD from Rear Cover



(Screw Torque: 3.0-3.5kgf)

S13 Remove FFC cables from Rear Cover, CTRL BD and CTRL+KEY BD

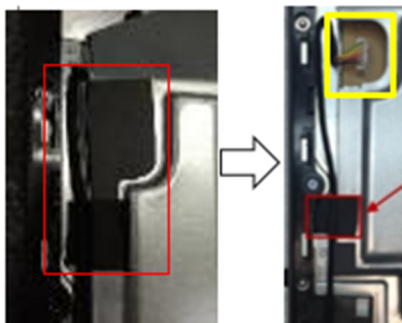
Unlock 6 screws to disassemble CTRL BD and CTRL+KEY BD from Rear Cover



(Screw Torque: 2.0±0.5kgf)

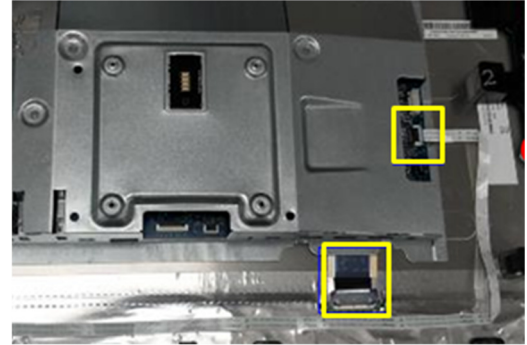
S14 Tear off mylar and all tapes from Backlight Wire on Main SHD

Unplug Backlight Wire from SPS BD

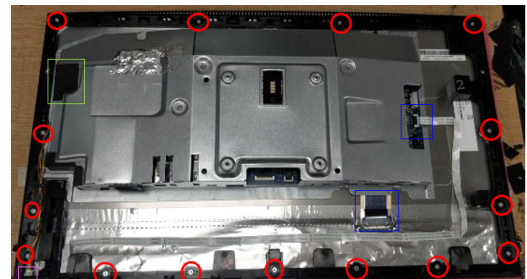


S15 Unplug "Power LENS FFC cable" from I/F BD and tear off "Power LENS FFC cable" from the panel

Unplug EDP FFC Cable between panel and I/F BD



S16 Unlock 15 screws to disassemble Middle Frame from Panel



(Screw Torque: 4.0±0.5kgf)

S17 Take off Main SHD from Panel and disassemble Middle Frame from Panel



S18 Tear off a tape on backlight wire and unplug backlight wire from panel



S19 Unlock 2 screws to disassemble Power Button module from middle frame



(Screw Torque: 2.0±0.5kgf)

S20 Unplug Power LENS FFC cable from "LENS BD" (Power LENS BD)



S21 Disassemble "MYLAR CTRL-BD" from "LENS BD" (Power LENS BD)



S22 Unlock 2 screws to disassemble "LENS BD" (Power CTRL BD) from Power Button



(Screw Torque: 2.0±0.5kgf)

S23 Unlock 1 screw on Docking BD

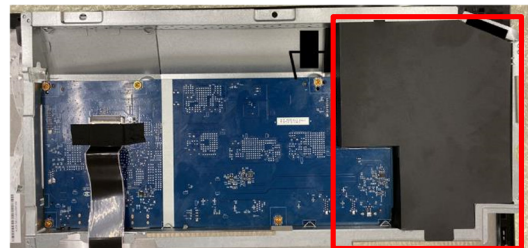


(Screw Torque: 8.5±1.0 kgf)

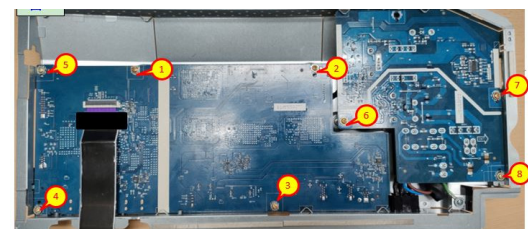
S24 Disassemble "I/F BD to Docking BD wire" from Docking BD



S25 Take off "MYLAR PWR-BD" from Main SHD



S26 Tear off the adhesive tape on "FFC EDP" and unplug "FFC EDP" from I/F BD, then, Unlock 8 PCBA screws

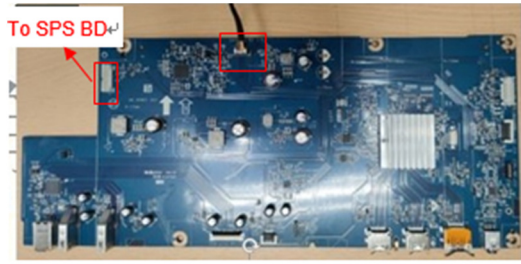


(Screw Torque: 8.5±1.0kgf)

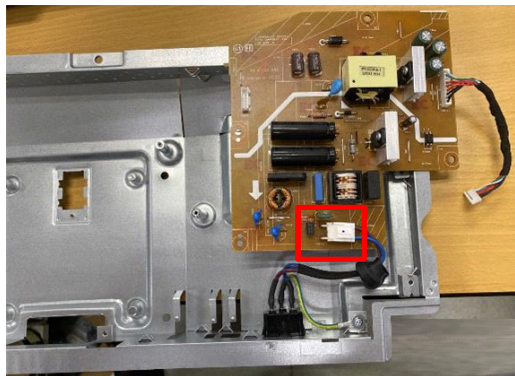
S27 Disassemble I/F BD from Main SHD



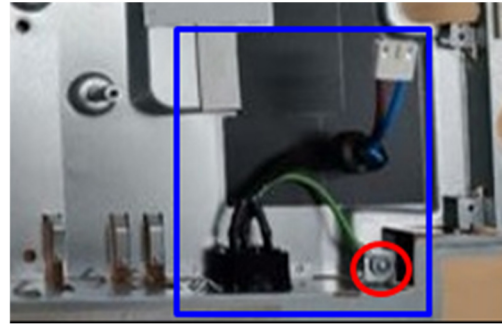
S28 Disassemble wires from I/F BD



S29 Disassemble SPS BD from Main SHD and disassemble "AC Socket Wire" from SPS BD



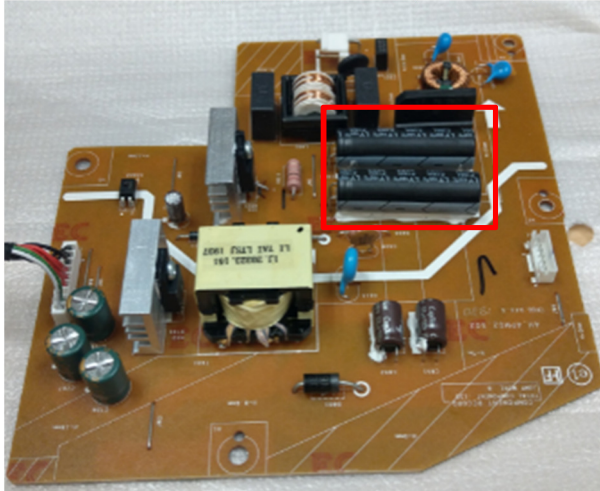
S30 Unlock 1 ground screw and disassemble AC power socket from Main SHD



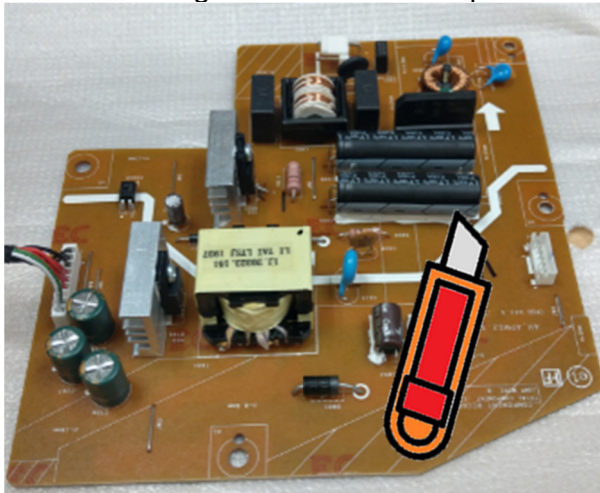
(Screw Torque: 8.5±1.0 kgf)

S31

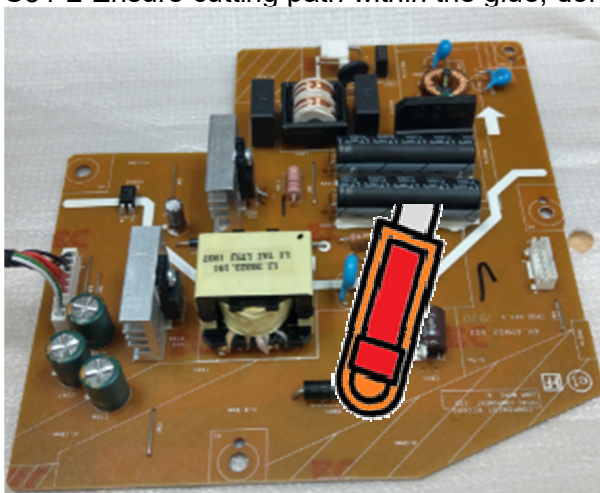
Remove electrolyte capacitors (red mark) from printed circuit boards



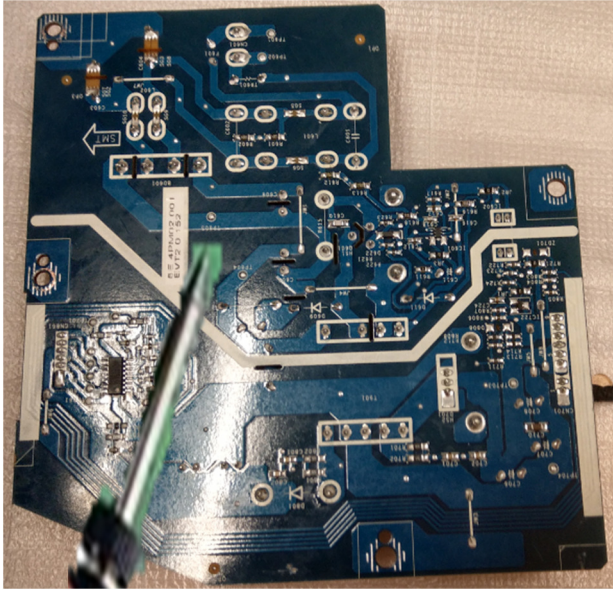
S31-1 Cut the glue between bulk cap. and PCB with a knife



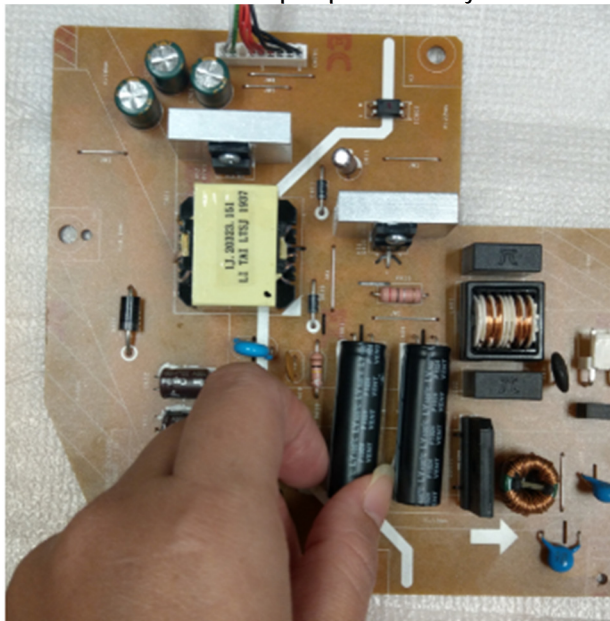
S31-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S31-3 Take out bulk cap. pin solder with soldering iron and absorber



S31-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater than 10 square cm)	Product has printed circuit boards (with a surface greater than 10 square cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and HC	No used
Gas discharge lamps	No used
LCD display > 100 cm ²	Product has an LCD greater than 100 cm ²
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Product has electrolyte capacitors (height >25mm, diameter > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber